

## AMENDMENTS TO THE SPECIFICATION

Please amend paragraph [0120] of the application as follows

[0120] ~~A method of applying a conductive carbon coating to a non-conductive surface and a printed wiring board having through holes or other nonconductive surfaces treated with such carbon coatings are disclosed. A conditioning agent is applied to the non-conductive surface to form a conditioned surface. A liquid dispersion of electrically conductive carbon (for example, graphite) having a mean particle size no greater than about 50 microns, combined with a organic binding agent, is coated on the conditioned surface to form an electrically conductive carbon coating. The conductive carbon coating is then optionally fixed on the (formerly) nonconductive surface and dried. The resulting coating has a low electrical resistance and is tenacious enough to be placed and exposed to molten solder without creating voids or losing adhesion, yet is easily removable from copper surfaces of the substrate by microetching. A printed wiring board comprising conductive layers separated by nonconductive material and having through holes or other nonconductive surfaces on which an electrically conductive carbon coating is formed. The conductive carbon coating includes electrically conductive carbon having a mean particle size not greater than about 1 micron and a water-dispersible organic binding agent. The conductive carbon coating formed on the nonconductive surfaces has a low electrical resistance and is tenacious enough to be plated and exposed to molten solder without creating voids or losing adhesion.~~